

Features

- Ideal for automated placement
- Superior Reverse Avalanche Capability
- +175°C Operation Junction Temperature
- Low power loss, high efficiency, High Reliability
- High temperature soldering guaranteed:
260°C/10 seconds
- Component in accordance to
RoHS 2011/65/EU and WEEE 2002/96/EC

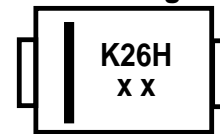


SOD-123FL

Mechanical Date

- **Case:** SOD-123FL
The plastic package carries Underwriters Laboratory
Flammability Classification 94V-0
- **Terminals:** Solder plated, solderable per
MIL-STD-750, Method 2026
- **Polarity:** Polarity symbols marked on case
- **Mounting Position:** Any

Marking



K26=Product Type Marking Code
H = High junction temperature
XX = Date Code

Maximum Ratings & Thermal Characteristics (T_A=25°C unless otherwise noted)

Items	Symbol	SBR2M60S1F	Unit
Maximum repetitive peak reverse voltage	V _{RRM}	60	V
Maximum RMS voltage	V _{RMS}	42	V
Maximum DC blocking voltage	V _{DC}	60	V
Average forward rectified current	I _{F(AV)}	2.0	A
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	I _{FSM}	50.0	A
Thermal resistance from junction to lead ⁽¹⁾	R _{θJL}	25.0	°C/W
Thermal resistance from junction to ambient ⁽¹⁾	R _{θJA}	80.0	°C/W
Operating junction and storage temperature range	T _J , T _{STG}	-65 to +175	°C

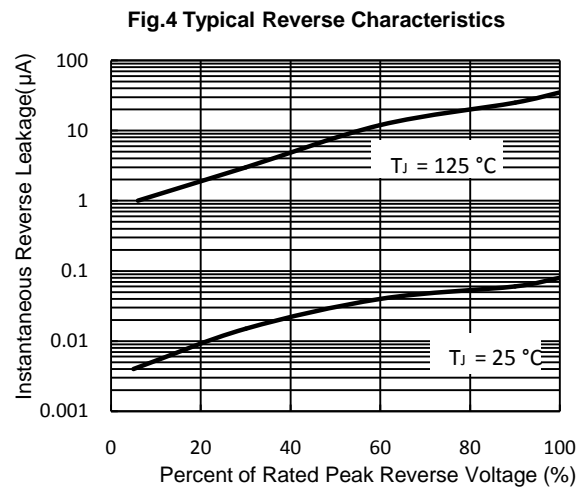
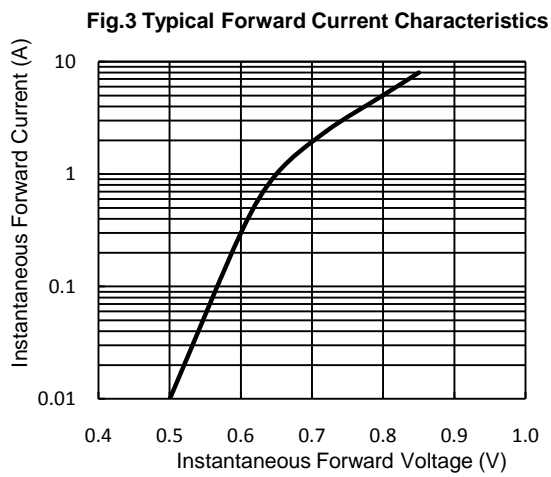
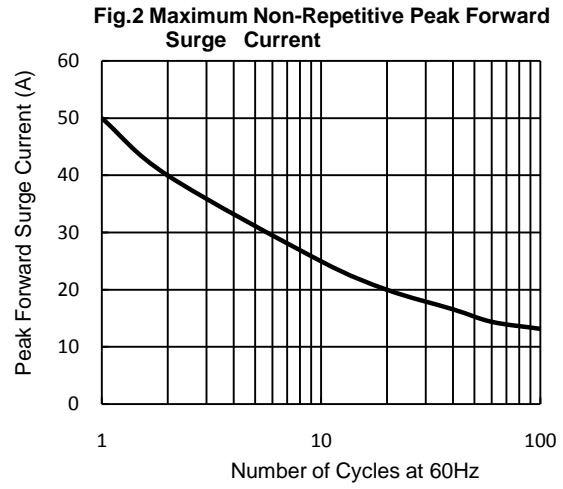
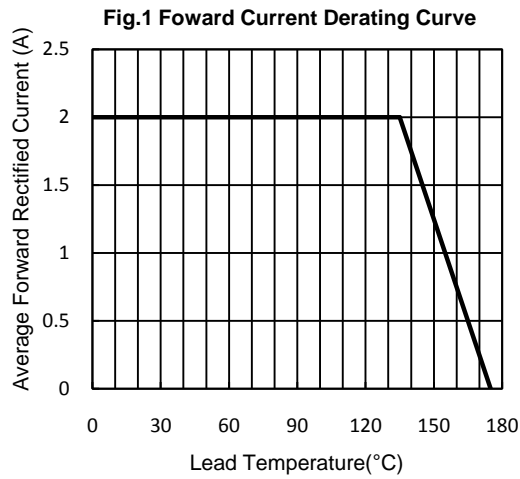
Note 1: Mounted on P.C.B. with 0.036 x 0.06" (0.9 x 1.5mm) copper pad areas.

Electrical Characteristics (T_A = 25 °C unless otherwise noted)

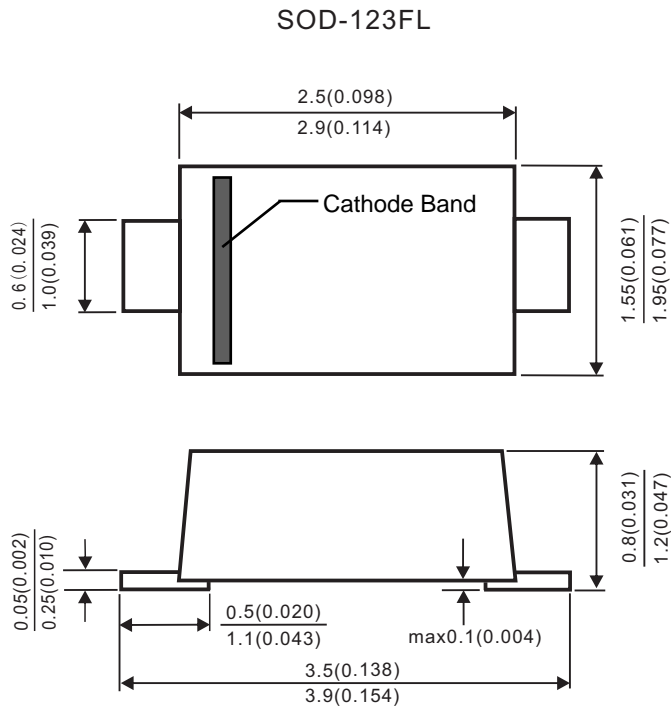
Items	Test conditions	Symbol	Min	Typ	Max	Unit
Instantaneous forward voltage	I _F =1A ⁽²⁾ , T _J =25°C	V _F	-	0.65	-	V
	I _F =2A ⁽²⁾ , T _J =25°C		-	-	0.74	
Reverse current	V _R =V _{DC}	I _R	-	0.1	0.7	μA
			T _J =125°C	-	60.0	

Note 2: Pulse test: 300μs pulse width, 1% duty cycle.

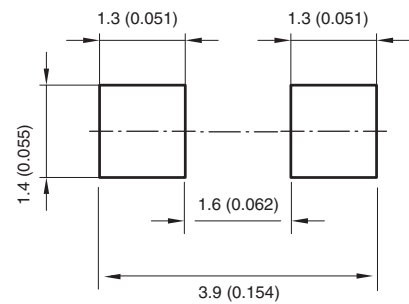
Characteristics Curves



Package Outline



Mounting Pad Layout



Dimensions in millimeters and(inches)

Ordering Information

Outline	Reel (PCS)	Per Carton (PCS)	Reel Diameters (mm)
Taping	3,000		178/7"